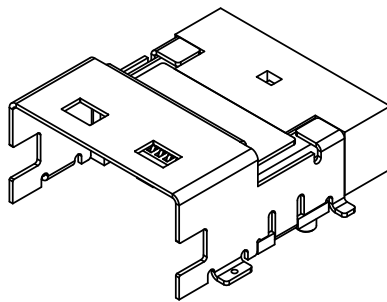
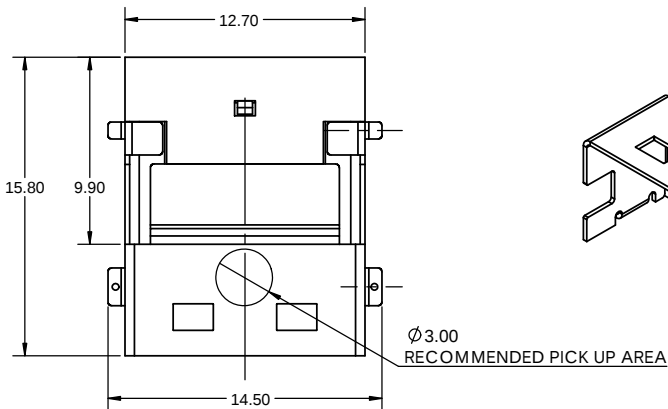


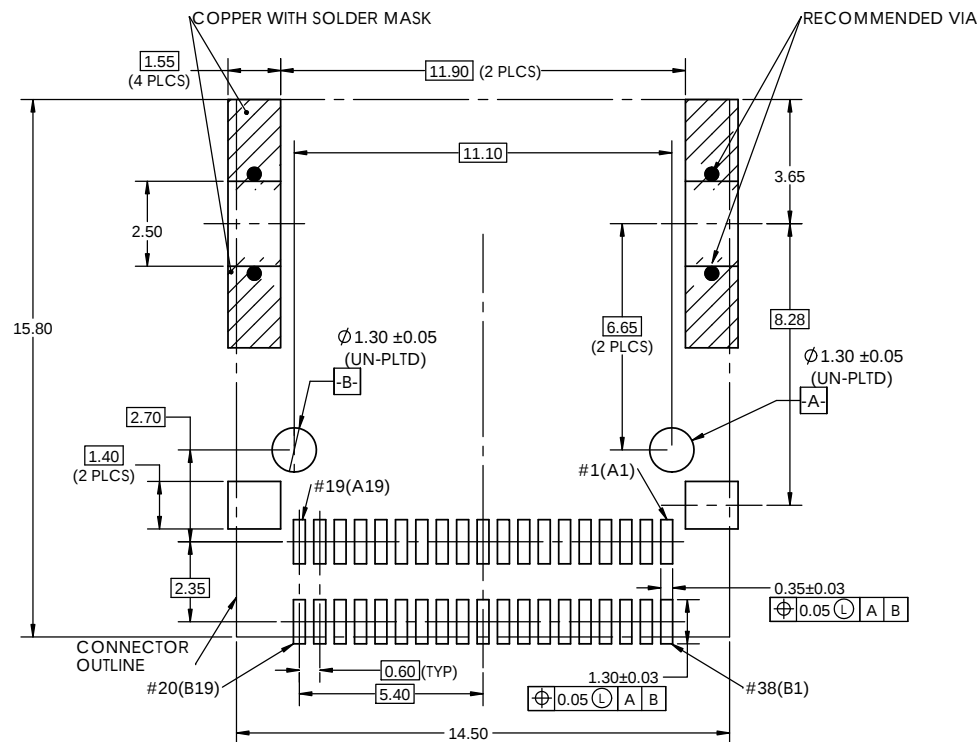
U10 - C038 - X 1 X X

OPTIONS

- 0T** = STANDARD CONSTRUCTION WITH TAPE & REEL PACKAGING
1T = NO RESONANCE DAMPING WITH TAPE & REEL PACKAGING

CONTACT PLATING OPTION

- 2** = 30 MICROINCHES OF GOLD ON MATING END WITH 100 MICROINCHES MINIMUM OF MATTE TIN ON SOLDER TERMINATION. 50-75 MICROINCHES OF NICKEL UNDERPLATE ALL OVER
3 = 15 MICROINCHES OF GOLD ON MATING END WITH 100 MICROINCHES MINIMUM OF MATTE TIN ON SOLDER TERMINATION. 50-75 MICROINCHES OF NICKEL UNDERPLATE ALL OVER



NOTES:

1) MATERIAL:

HOUSING: SOLDER REFLOW PROCESS COMPATIBLE LCP, UL94V-0
CONTACTS: HIGH PERFORMANCE COPPER ALLOY
LATCH: PHOSPHOR BRONZE
RESONANCE DAMPENING FEATURE: SEMI-CONDUCTIVE POLYMER

2) RoHS COMPLIANT



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UNLESS SPECIFIED OTHERWISE		DRAWN	J.SI	DEC12/14	Amphenol High Speed Interconnects A Division of Amphenol Corp. www.amphenolcanada.com ULTRAPORT SLIMSAS™ 4X24 R/A RECEPTACLE WITH SMT LATCH						
PRIMARY UNITS MILLIMETERS		CHECKED									
SECONDARY		M.E. APP'D									
REFERENCE IN PARENTHESES		Q.A. APP'D									
GENERAL TOLERANCES		DWG APP'D			DWG. NO.						
1 DECIMAL PLACE	±0.35	ENG. REL. NO.		ECN TBD							
2 DECIMAL PLACES	±0.25	REF.			P-U10-C038-X1XX						
3 DECIMAL PLACES	±0.15	THIRD ANGLE PROJECTION									
ANGULAR DEGREES	±2°				REV F						
		DO NOT SCALE DRAWING			CODE ID NO.	03554	DWG SIZE:	C	SCALE:	5:1	SHEET 1 OF 1